

NOVASTACK® 35-HDN

Ideal for 5G mmWave antenna module and devices, fully-shielded and narrow design, Power supply is available with Corson Alloy contact, 0.35 mm pitch, 0.7 mm height

Product Specifications:

Board Pitch (mm)	0.35	
Wiping Length (mm)	0.14	
Mated Size (mm)	Height	0.7 +/- 0.05
	Width	Formula: 4.15 (10 P), 5.90 (20 P), 7.90 (30 P)
	Depth	2.15 mm
Frequency	DC ~ 15 GHz	
Current Rating	Signal	1.0 A / pin (Max. 10 P) (12 P and over : 12.0 A AC/DC (Total))
	Power	-
Pin Counts	Range	10 - 60
	Available	10, 20, 30

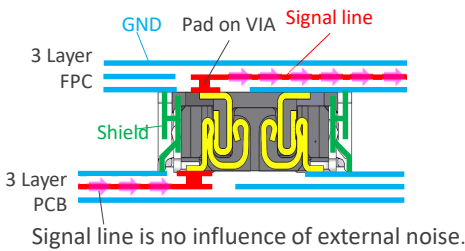
* Please inquire for pin counts not listed or outside of the pin count range.

Applicable Standards (Reference Only):

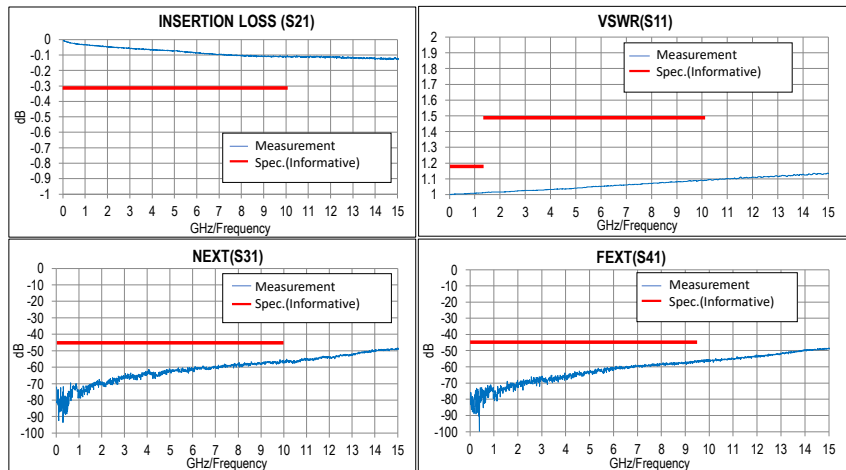
USB4 (20 Gbps/lane) USB 3.1 Gen 2 (10 Gbps)



► Ideal for high frequency applications (5G mmWave, USB4 / Thunderbolt 4, etc.)

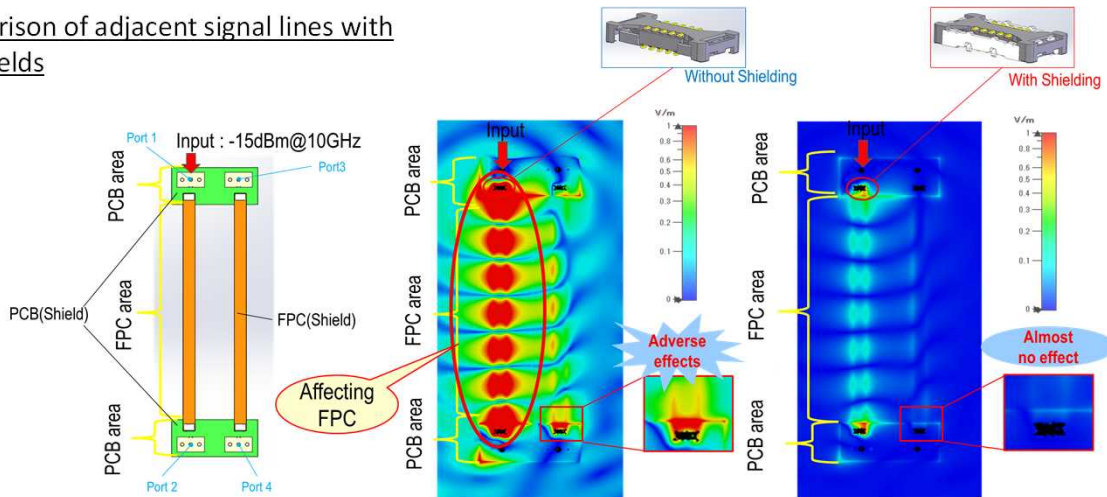


◆ Pin assignment



► ZenShield® fully-shielded design, decreases EMI issue caused by 5G applications

E-Field comparison of adjacent signal lines with or without shields



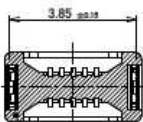
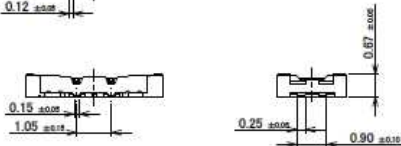
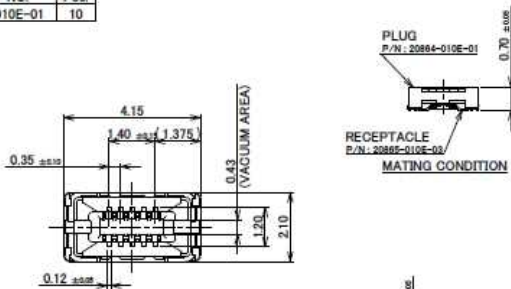
► Narrow depth and low height, fully-shielded board-to-board connector



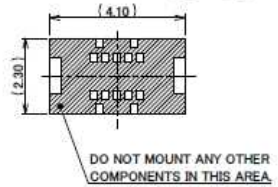
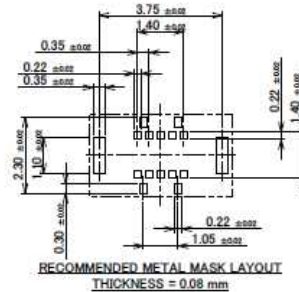
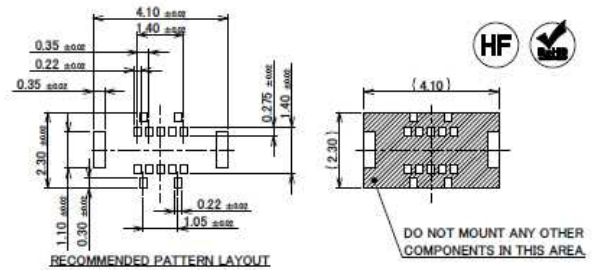
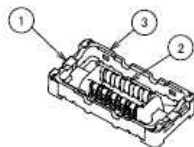
Component Parts Detail

Plug Assembly

Recommended P/N		20864-010E-01
PART NO.	Pos.	
20864-010E-01	10	



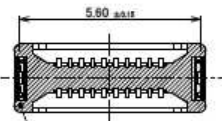
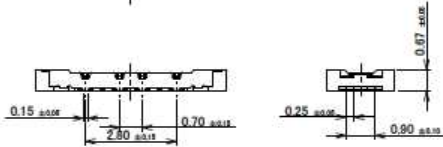
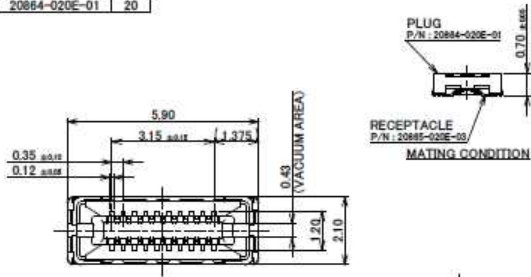
There is a possibility of dent shape in the bottom surface of HOUSING.



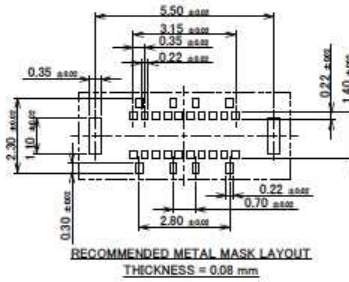
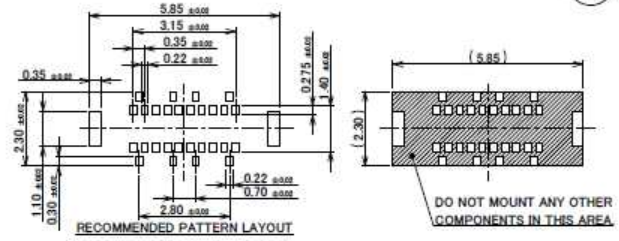
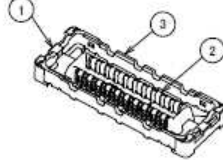
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK

Plug Assembly

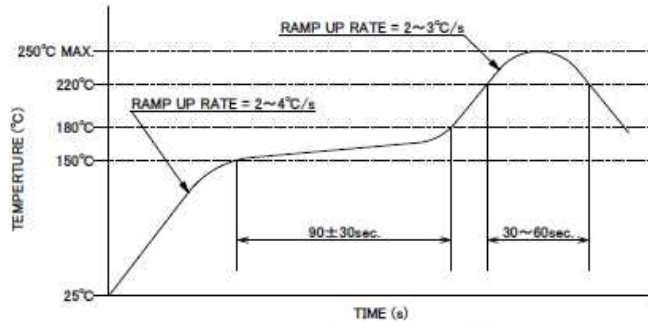
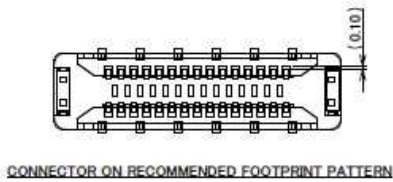
Recommended P/N		20864-020E-01
PART NO.	Pos.	
20864-020E-01	20	



There is a possibility of dent shape in the bottom surface of HOUSING.



NO.	DISCRPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
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1	HOUSING	LCP	UL94V-0, BLACK



Rev.8

Rev.8

Plug Assembly

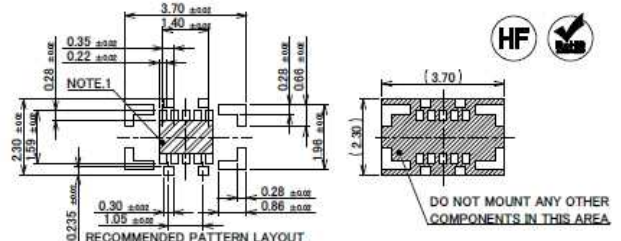
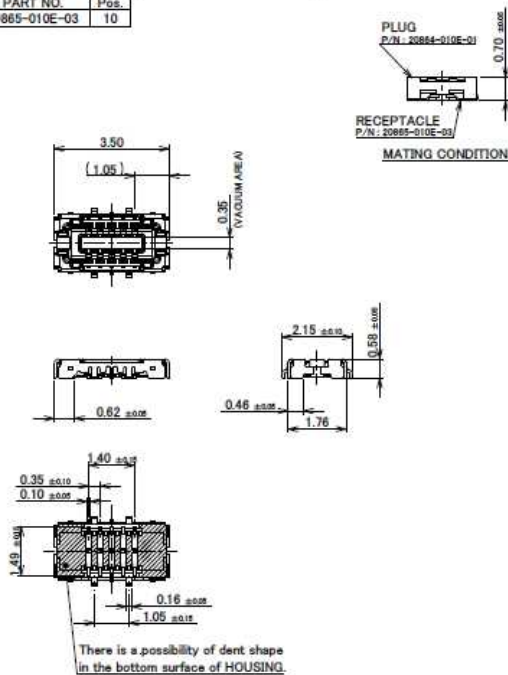
ITEMS	SPECIFICATION
RATING VOLTAGE	60V AC(r.m.s) / DC (PER A CONTACT)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : \leq 40mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : \leq 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18022
INSTRUCTION MANUAL	HIM-16019
APPEARANCE CRITERIA No.	QLS-A***

Rev.8

Receptacle Assembly

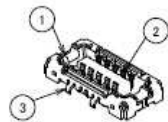
Recommended P/N 20865-010E-03

PART NO.	Pos.
20865-010E-03	10



NOTES:
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

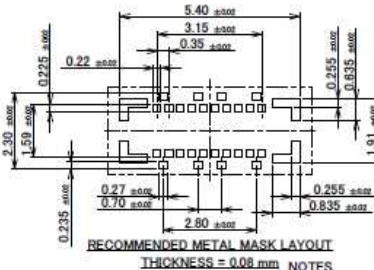
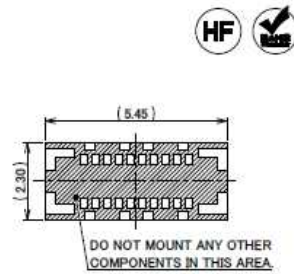
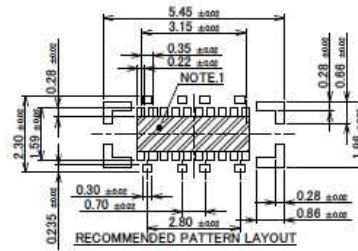
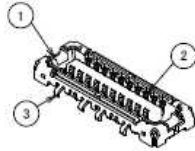
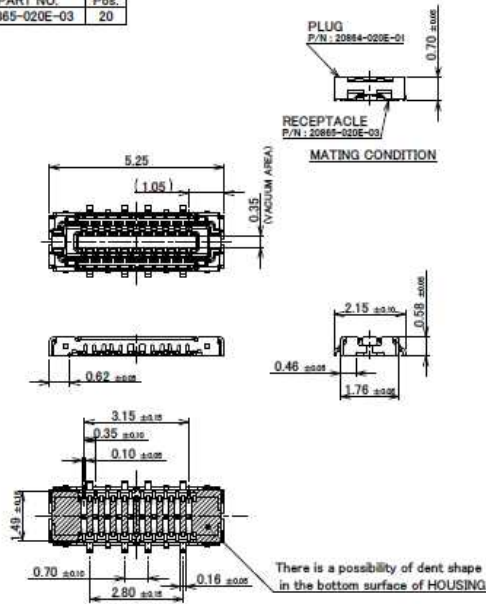
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Rev.8

Receptacle Assembly

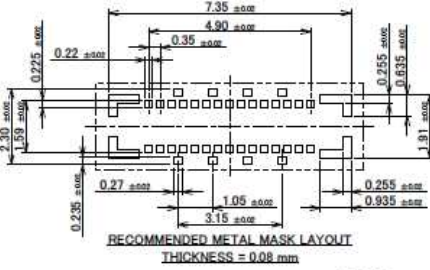
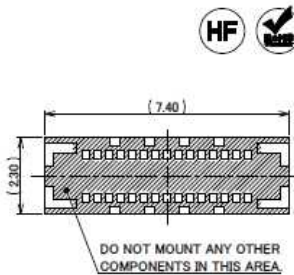
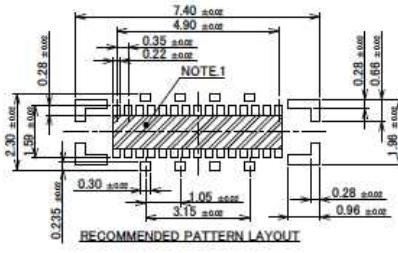
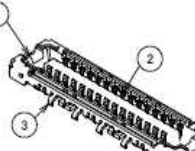
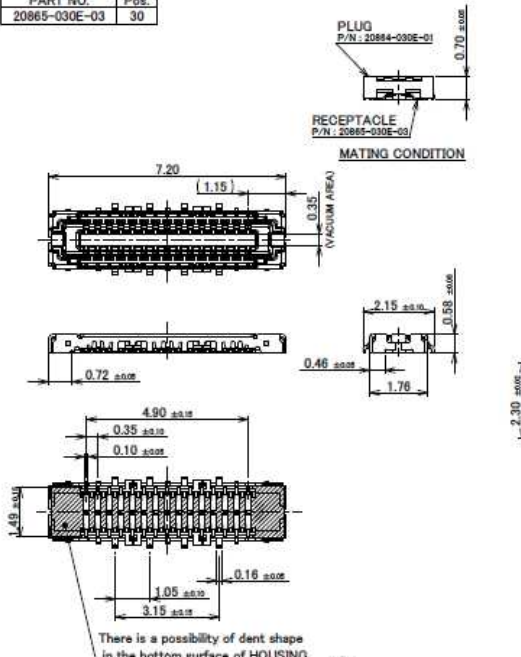
Recommended P/N		20865-020E-03
PART NO.	Pos.	
20865-020E-03	20	



THICKNESS = 0.08 mm
 NOTES
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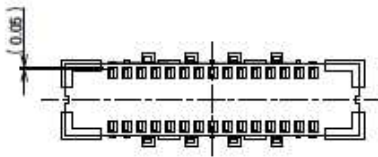
Recommended P/N		20865-030E-03
PART NO.	Pos.	
20865-030E-03	30	



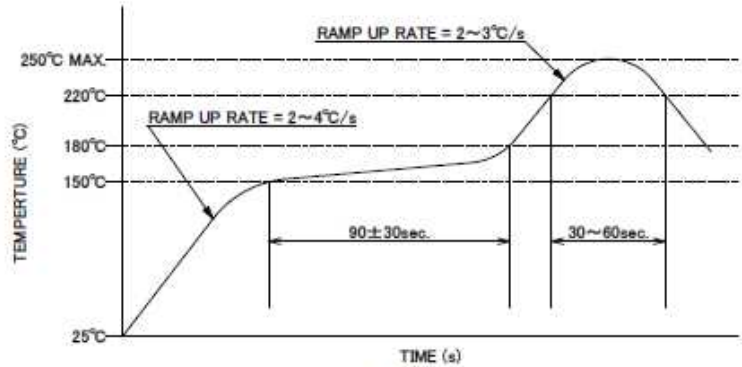
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Receptacle Assembly



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.8

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PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18023
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

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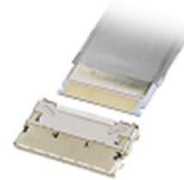
Board to Board



High-Density



Autolocking FPC/FFC



High-Density



FPC/FFC



Micro-Coaxial / Discrete Cable



High-Speed



RF



High-Frequency



Optical Module



High-Speed



Power



High-Power



I/O (Input/Output)



Quick charge

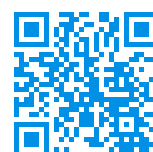


Effector



Custom Connectors Available

Inquiry



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Contact your sales representative or more detailed information.

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